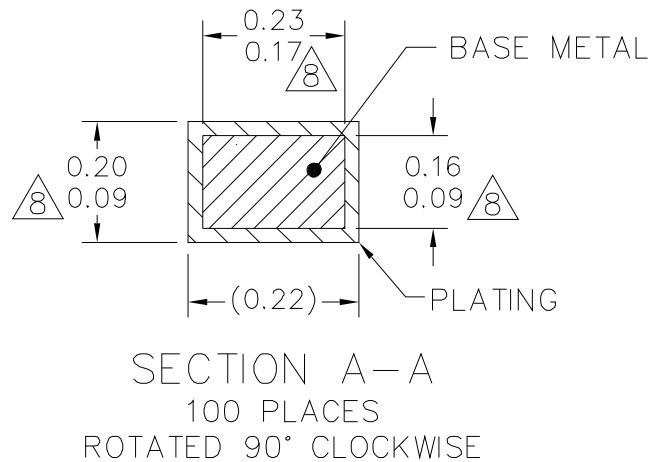
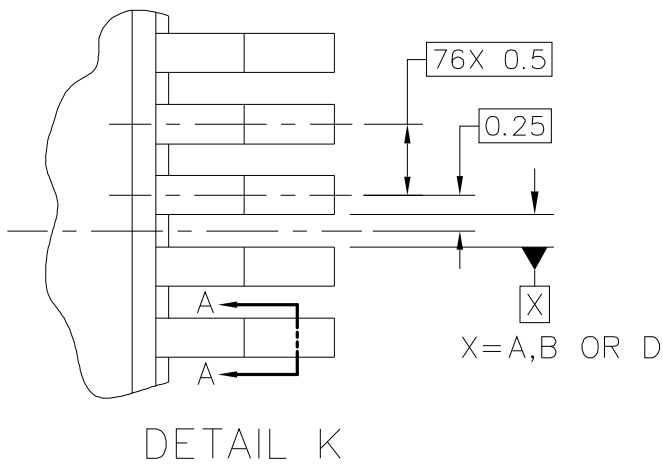
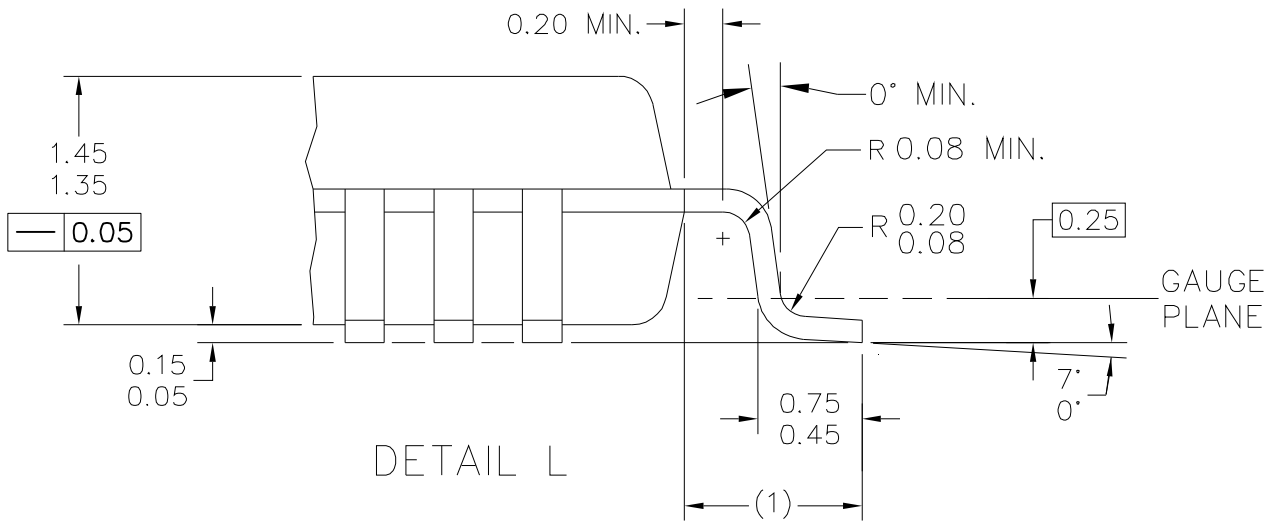
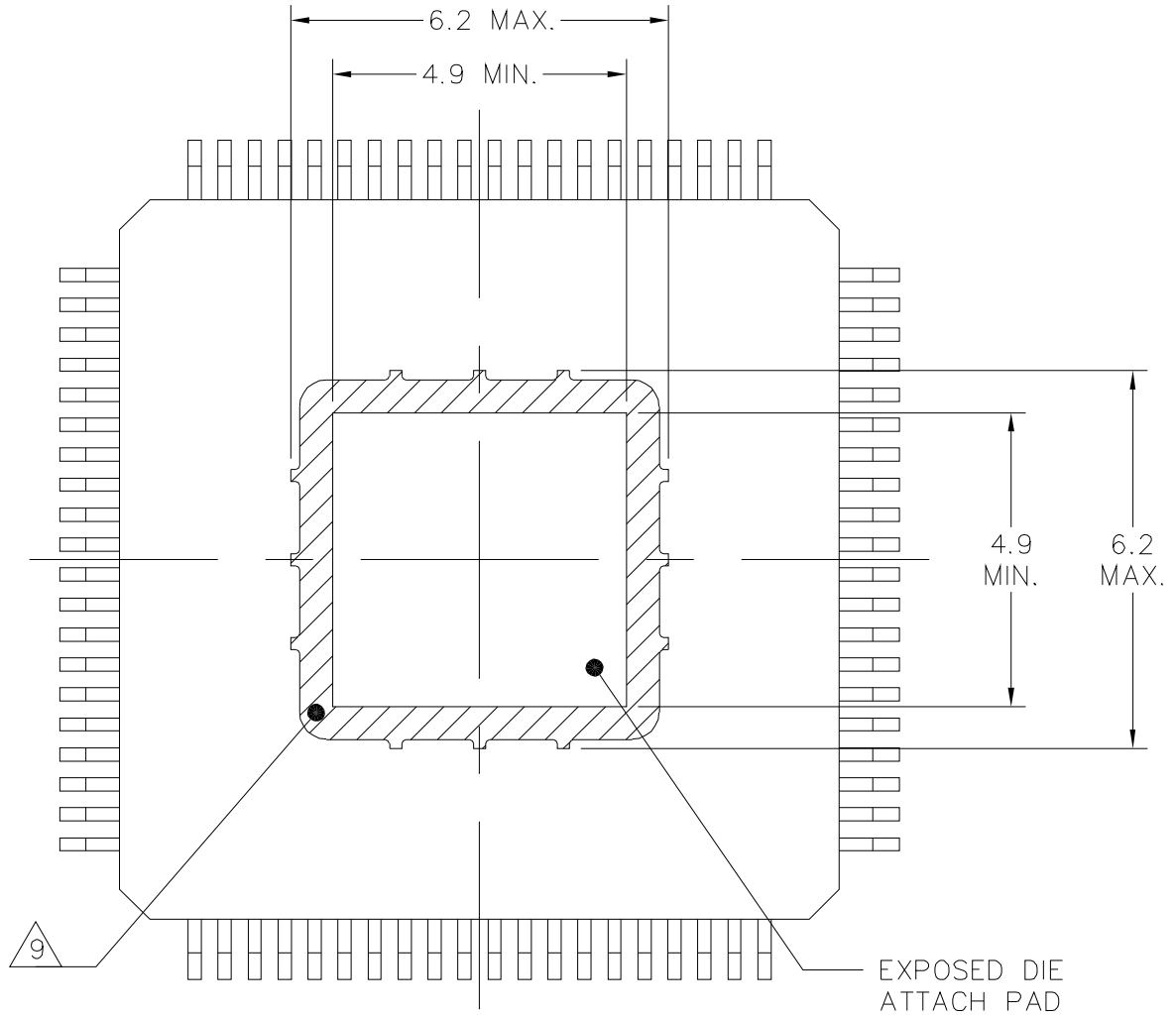


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: LQFP, 12 X 12 X 1.4 PKG, 0.5 PITCH, 80 I/O, 5.6 X 5.6 EXPOSED PAD		DOCUMENT NO: 98ASA00505D	REV: A
		STANDARD: NON-JEDEC	
		SOT1572-1	11 JAN 2016



© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: LQFP, 12 X 12 X 1.4 PKG, 0.5 PITCH, 80 I/O, 5.6 X 5.6 EXPOSED PAD		DOCUMENT NO: 98ASA00505D	REV: A
		STANDARD: NON-JEDEC	
		SOT1572-1	11 JAN 2016



VIEW J-J

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE	
TITLE: LQFP, 12 X 12 X 1.4 PKG, 0.5 PITCH, 80 I/O, 5.6 X 5.6 EXPOSED PAD		DOCUMENT NO: 98ASA00505D	REV: A
		STANDARD: NON-JEDEC	
		SOT1572-1	11 JAN 2016



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM DIMENSION BY MORE THAN 0.08 MM. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 MM.
6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. DIMENSIONS ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 MM AND 0.25 MM FROM THE LEAD TIP.
9. HATCHED AREA TO BE KEEP–OUT ZONE FOR PCB ROUTING.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	<b>MECHANICAL OUTLINE</b>	PRINT VERSION NOT TO SCALE
TITLE: LQFP, 12 X 12 X 1.4 PKG, 0.5 PITCH, 80 I/O, 5.6 X 5.6 EXPOSED PAD	DOCUMENT NO: 98ASA00505D	REV: A
	STANDARD: NON–JEDEC	
	SOT1572–1	11 JAN 2016